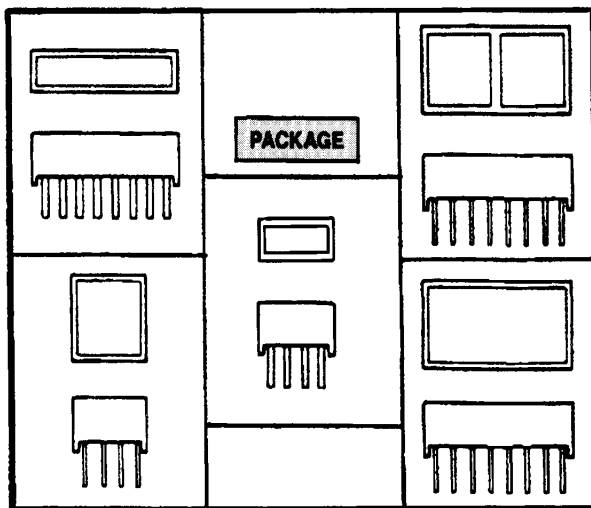


HIGH EFFICIENCY RED HLMP-2300/2600 SERIES
YELLOW HLMP-2400/2700 SERIES
HIGH EFFICIENCY GREEN HLMP-2500/2800 SERIES



DESCRIPTION

These LED Light Bar series are bright, large emitting area, rectangular devices that are designed for backlighting legend/message annunciators.

These devices are offered in single-in-line and dual-in-line packages that contain single or segmented light-emitting area. Each package style is offered in High Efficiency Red, Yellow, or Green emission color.

FEATURES

- Large area, uniform, bright light-emitting surfaces
- Select from six package styles
- Choice of three colors
- Categorized for intensity and color
- X-Y stackable
- Easily driven with I.C.s
- Alternate source for popular backlighting components

MODEL NUMBERS

| PART NO. | COLOR | DESCRIPTION | | PACKAGE | PIN OUT |
|-------------------------------------|--|--|--|---------|---------|
| HLMP-2300 HLMP-2400 HLMP-2500 | High Efficiency Red Yellow High Efficiency Green | 2 LED Single-in-line 0.35 in. x 0.15 in. Area | | A | A |
| HLMP-2350 HLMP-2450 HLMP-2550 | High Efficiency Red Yellow High Efficiency Green | 4 LED Single-in-line 0.75 in. x 0.15 in. Area | | B | B |
| HLMP-2655 HLMP-2755 HLMP-2855 | High Efficiency Red Yellow High Efficiency Green | 4 LED Dual-in-line 0.35 in. x 0.35 in. Area | | C | C |
| HLMP-2670 HLMP-2770 HLMP-2870 | High Efficiency Red Yellow High Efficiency Green | Dual 0.35 in. x 0.35 in. Area Dual-in-line package | | D | D |
| HLMP-2685 HLMP-2785 HLMP-2885 | High Efficiency Red Yellow High Efficiency Green | 8 LED 0.35 in. x 0.75 in. Area Dual-in-line package | | E | D |

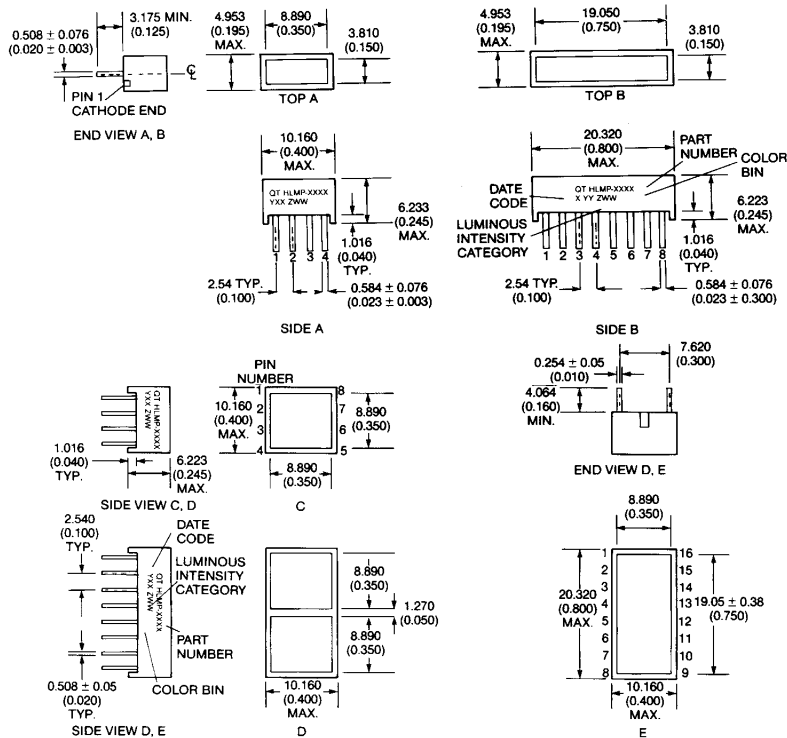
ABSOLUTE MAXIMUM RATINGS $T_A=25^\circ\text{C}$ (Unless Otherwise Stated)

| | HIGH EFFICIENCY RED HIGH EFFICIENCY GREEN HLMP-2300/-2500 -2600/-2800 SERIES | YELLOW HLMP-2400/ -2700 SERIES |
|--|---|--|
| Power dissipation per LED chip (See Note 1) | 135 mW | 85 mW |
| Peak forward current per LED chip, $T_A=50^\circ\text{C}$ (max. pulse width=2 ms) (See Notes 1 and 2) | 90 mA | 60 mA |
| Average forward per LED chip pulsed conditions, $T_A=50^\circ\text{C}$ (See Note 2) | 25 mA | 20 mA |
| DC forward current per LED chip, $T_A=50^\circ\text{C}$ (See Note 3) | 30 mA | 25 mA |
| Reverse voltage per LED chip | 6V | 6V |
| Storage and operating temperature range | -40°C to $+85^\circ\text{C}$ | -40°C to $+85^\circ\text{C}$ |
| Soldering time at 260°C (See Note 4) | 260°C for 3 sec. | 260°C for 3 sec. |

NOTES

- For HLMP-2300/-2500/-2600/-2800 Series, derate above $T_A=25^\circ\text{C}$ at $1.8\text{ mW}/^\circ\text{C}$ per LED chip. For HLMP-2400/-2700 Series, derate above $T_A=50^\circ\text{C}$ at $1.8\text{ mW}/^\circ\text{C}$ per LED chip.
- See Figure 1/2 to establish pulse operating conditions.
- For HLMP-2300/-2500/-2600/-2800 Series, derate above $T_A=50^\circ\text{C}$ at $0.5\text{ mA}/^\circ\text{C}$ per LED chip. For HLMP-2400/-2700 Series derate above $T_A=60^\circ\text{C}$ at $9.5\text{ mA}/^\circ\text{C}$ per LED chip.
- Lead immersed to 1/16 in. from body of the device. Maximum unit surface temperature is 140°C .

PACKAGE DIMENSIONS



NOTE: DIMENSIONS IN MILLIMETERS (INCHES). TOLERANCES ± 0.25 (± 0.010) UNLESS OTHERWISE INDICATED

| ELECTRO-OPTICAL CHARACTERISTICS (T_A=25°C) | | | | | | | | | |
|---|--------|-----------------|-------|-------|-------|-------|------|-------------------|------------------------------------|
| HIGH EFFICIENCY RED | | | | | | | | | |
| PARAMETER | SYMBOL | HLMP | | | | | UNIT | TEST CONDITIONS | |
| | | -2300 | -2350 | -2655 | -2670 | -2685 | | | |
| Luminous Intensity | min. | | 6.0 | 13 | 13 | 13 | 22 | mcd | I _F =20 mA |
| | typ. | I _V | 23 | 45 | 43 | 45 | 80 | mcd | I _F =20 mA |
| Forward voltage | typ. | | 30 | 50 | 50 | 50 | 100 | mcd | I _F =60 mA pK, 1:3 D.F. |
| | max. | V _F | 2.6 | 2.6 | 2.6 | 2.6 | 2.6 | V | I _F =20 mA |
| Peak wavelength | typ. | λ _p | 2.0 | 2.0 | 2.0 | 2.0 | 2.0 | V | I _R =100 μA |
| | | | 630 | 630 | 630 | 630 | 630 | nm | |
| Dominant wavelength | typ. | λ _d | 626 | 626 | 626 | 626 | 626 | nm | |
| Capacitance | typ. | C | 45 | 45 | 45 | 45 | 45 | pF | V _F =0, f=1 MHz |
| Reverse voltage | min. | V _R | 6 | 6 | 6 | 6 | 6 | V | I _R =100 μA |
| Thermal resistance | typ. | θ _{JL} | 150 | 150 | 150 | 150 | 150 | °C/W/ LED chip | |

| ELECTRO-OPTICAL CHARACTERISTICS (T_A=25°C) | | | | | | | | | |
|---|--------|-----------------|-------|-------|-------|-------|------|-------------------|------------------------------------|
| YELLOW | | | | | | | | | |
| PARAMETER | SYMBOL | HLMP | | | | | UNIT | TEST CONDITIONS | |
| | | -2400 | -2450 | -2755 | -2770 | -2785 | | | |
| Luminous Intensity | min. | | 6 | 13 | 13 | 13 | 26 | mcd | I _F =20 mA |
| | typ. | I _V | 20 | 38 | 35 | 35 | 70 | mcd | I _F =20 mA |
| Forward voltage | typ. | | 33 | 60 | 60 | 60 | 115 | mcd | I _F =60 mA pK, 1:3 D.F. |
| | max. | V _F | 2.6 | 2.6 | 2.6 | 2.6 | 2.6 | V | I _F =20 mA |
| Peak wavelength | typ. | λ _p | 2.1 | 2.1 | 2.1 | 2.1 | 2.1 | V | I _R =100 μA |
| | | | 585 | 585 | 585 | 585 | 585 | nm | |
| Dominant wavelength | typ. | λ _d | 588 | 588 | 588 | 588 | 588 | nm | |
| Capacitance | typ. | C | 35 | 35 | 35 | 35 | 35 | pF | V _F =0, f=1 MHz |
| Reverse voltage | min. | V _R | 6 | 6 | 6 | 6 | 6 | V | I _R =100 μA |
| Thermal resistance | typ. | θ _{JL} | 150 | 150 | 150 | 150 | 150 | °C/W/ LED chip | |

| ELECTRO-OPTICAL CHARACTERISTICS (T_A=25°C) | | | | | | | | | |
|---|--------|-----------------|-------|-------|-------|-------|------|-------------------|------------------------------------|
| HIGH EFFICIENCY GREEN | | | | | | | | | |
| PARAMETER | SYMBOL | HLMP | | | | | UNIT | TEST CONDITIONS | |
| | | -2500 | -2550 | -2855 | -2870 | -2885 | | | |
| Luminous Intensity | min. | | 5 | 11 | 11 | 11 | 22 | mcd | I _F =20 mA |
| | typ. | I _V | 25 | 50 | 50 | 50 | 100 | mcd | I _F =20 mA |
| Forward voltage | typ. | | 38 | 75 | 75 | 75 | 150 | mcd | I _F =60 mA pK, 1:3 D.F. |
| | max. | V _F | 2.6 | 2.6 | 2.6 | 2.6 | 2.6 | V | I _F =20 mA |
| Peak wavelength | typ. | λ _p | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | V | I _R =100 μA |
| | | | 565 | 565 | 565 | 565 | 565 | nm | |
| Dominant wavelength | typ. | λ _d | 567 | 567 | 567 | 567 | 567 | nm | |
| Capacitance | typ. | C | 40 | 40 | 40 | 40 | 40 | pF | V _F =0, f=1 MHz |
| Reverse voltage | min. | V _R | 6 | 6 | 6 | 6 | 6 | V | I _R =100 μA |
| Thermal resistance | typ. | θ _{JL} | 150 | 150 | 150 | 150 | 150 | °C/W/ LED chip | |

TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES
(25°C Free Air Temperature Unless Otherwise Specified)

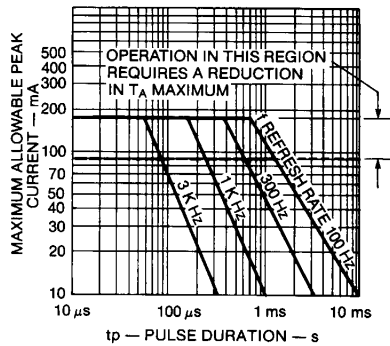


Fig. 1. Maximum Tolerable Peak Current per LED Chip vs. Pulse Duration for HLMP-23X0/-26XX/-25X0/-28XX

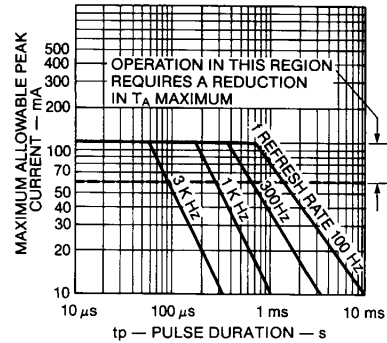


Fig. 2. Maximum Tolerable Peak Current per LED Chip vs. Pulse Duration for HLMP-24X0/-27XX Devices

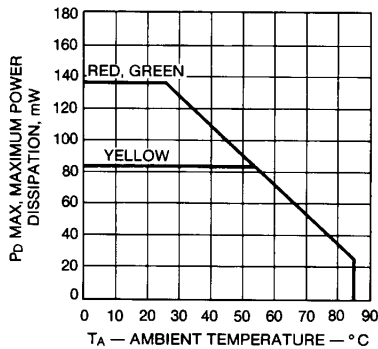


Fig. 3. Maximum Power Dissipation per LED vs. Ambient Temperature

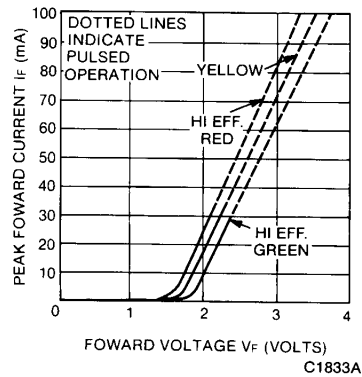


Fig. 4. Forward Current vs. Forward Voltage

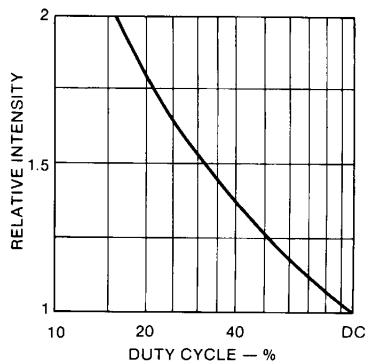


Fig. 5. Luminous Intensity vs. Duty Cycle

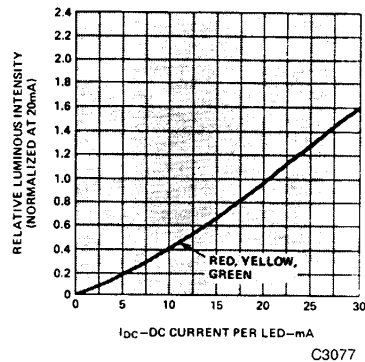
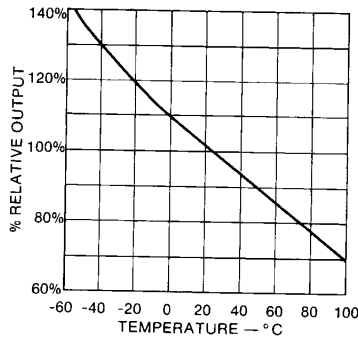


Fig. 6. Luminous Intensity vs. Forward Current

TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES
(25°C Free Air Temperature Unless Otherwise Specified) (Cont'd)



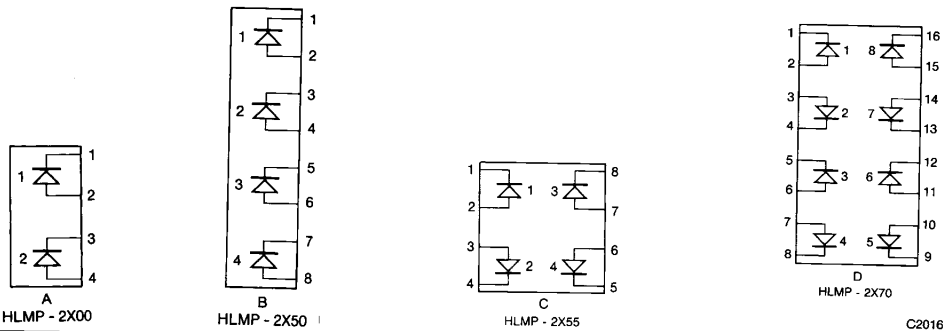
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Fig. 7. Output vs. Temperature

PIN CONNECTIONS TO ELECTRICAL SCHEMATIC

| PIN | ELECTRICAL CONNECTION | | | |
|-----|-----------------------|-----------|-----------|-----------------|
| | HLMP-2X00 | HLMP-2X50 | HLMP-2X55 | HLMP-2X70/-2X85 |
| 1 | 1 Cathode | 1 Cathode | 1 Cathode | 1 Cathode |
| 2 | 1 Anode | 1 Anode | 1 Anode | 1 Anode |
| 3 | 2 Cathode | 2 Cathode | 2 Cathode | 2 Cathode |
| 4 | 2 Anode | 2 Anode | 2 Anode | 2 Anode |
| 5 | | 3 Cathode | 3 Cathode | 3 Cathode |
| 6 | | 3 Anode | 3 Anode | 3 Anode |
| 7 | | 4 Cathode | 4 Cathode | 4 Cathode |
| 8 | | 4 Anode | 4 Cathode | 4 Anode |
| 9 | | | | 4 Cathode |
| 10 | | | | 5 Cathode |
| 11 | | | | 5 Anode |
| 12 | | | | 6 Anode |
| 13 | | | | 6 Cathode |
| 14 | | | | 7 Cathode |
| 15 | | | | 7 Anode |
| 16 | | | | 8 Anode |
| | | | | 8 Cathode |

ELECTRICAL SCHEMATIC



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